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**PRODUCT BULLETIN**  
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**17 Dec 2007**

**SUBJECT: ON Semiconductor Product Bulletin # 16076**

**TITLE: Discontinuance of Dry Pack for NCP1606xDR2G Products**

**PROPOSED FIRST SHIP DATE: 01 Jan 2008**

**AFFECTED PRODUCT DIVISION: Automotive and Power Regulation Group (APRG)**

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor sales office or Scott Brow <[Scott.Brow@onsemi.com](mailto:Scott.Brow@onsemi.com)>

**NOTIFICATION TYPE:**

ON Semiconductor considers this change approved unless specific conditions of acceptance are provided in writing. To do so, contact your local ON Semiconductor sales office.

**DESCRIPTION AND PURPOSE:**

The NCP1606xDR2G has recently been qualified at MSL 1 @ 260C level. 1 Production lot has passed MSL 1 @ 260C Preconditioning and reliability testing. Results are shown here:

Pre-Conditioned AutoClave – 121C/100%RH/15psig	0/80 at 96hrs
Pre-Conditioned Temp Cycle - -65C to +150C	0/80 at 500cycles
Pre-Conditioned UHAST – 130C/85%RH/18.8psig	0/80 at 96hrs
High Temperature Storage – 150C	0/80 at 504hrs
High Temp Operating Life – Ta = 125C, Vcc = 18V	0/80 at 504hrs

These devices were previously qualified to MSL 3 which required the use of Dry Packaging Techniques. Effective Jan 1, 2008, dry packing will be discontinued for these devices and the products will be shipped per MSL 1 packaging.

**AFFECTED DEVICE LIST**

NCP1606ADR2G  
NCP1606BDR2G